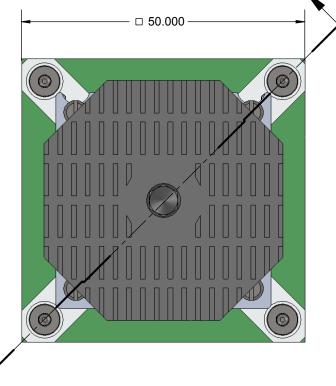
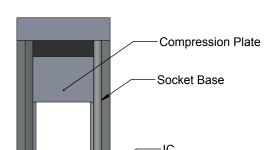
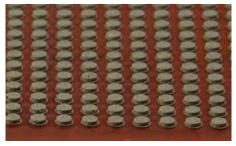
GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware
 High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
 Easily removable swivel socket lid

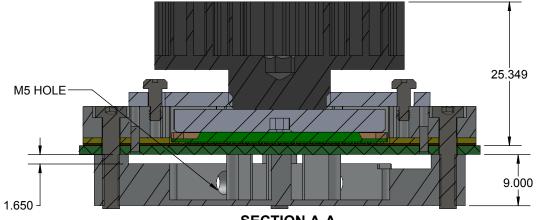






GT Elastomer Contactor

PROBE SLOT DETAIL



SECTION A-A

Description: GT-BGA 32x32 array 0.8mm pitch custom footprint

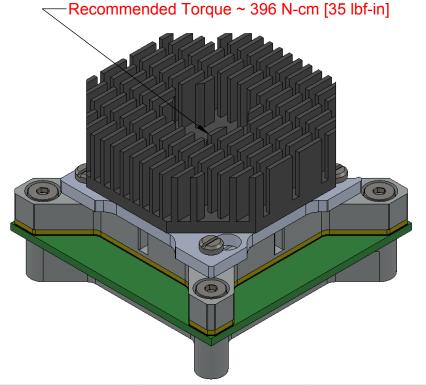
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

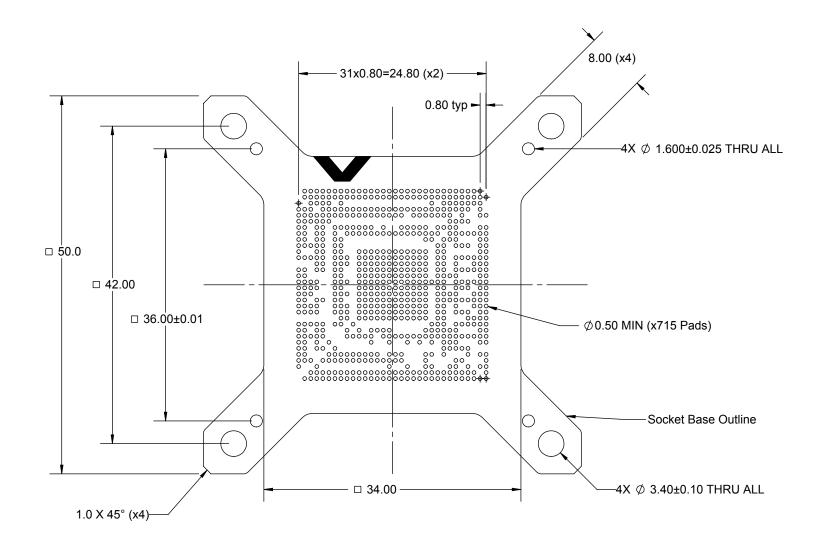
 $\frac{Tolerances:}{Lo.0254mm} \ [\pm 0.001"], Pitches (from true position) \pm 0.0762mm \ [\pm 0.003"], substrate thickness tolerance \pm 10\%, all other tolerances \pm 0.127mm \ [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.$

GT-BGA-2004 Drawing

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodélectronics.com

STATUS: Released	SHEET: 1 OF 5	REV. A
ENG: B. Schatz	DRAWN BY: D. Hauer	SCALE: 3:2
FILE: GT-BGA-2004 Dwg	DATE: 5/27/14	





Target PCB Recommendations

Total thickness: 1.6mm min. Plating: Gold or Solder Finish

PCB Pad Height: Same or higher than solder mask

Description: Recommended PCB Layout

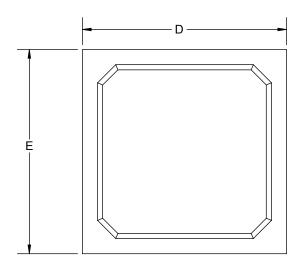
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

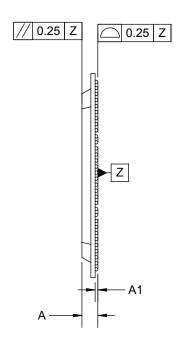
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

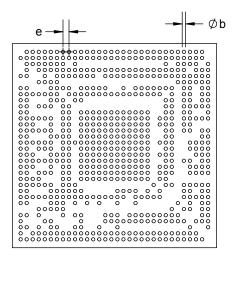
GT-BGA-2004 Drawing



STATUS: Released	SHEET: 2 OF 5	REV. A
ENG: B. Schatz	DRAWN BY: D. Hauer	SCALE: 2:1
FILE: GT-BGA-2004 Dwg	DATE: 5/27/14	







MIN

0.3

0.35

26.8

26.8

0.80

32 x32

1024

MAX

2.5

0.5

27.2

27.2

DIM

A A1

> b D

Ε

e Array

Max Ball Count*

Dimensions are in millimeters.

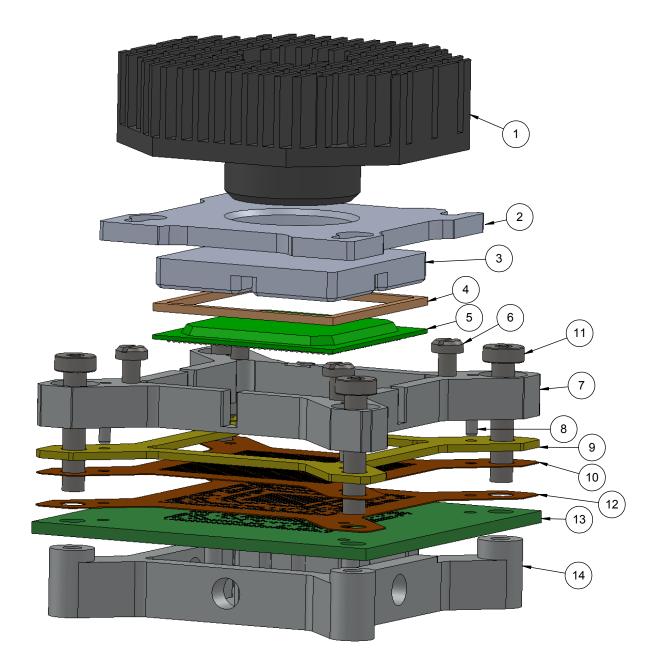
- 1. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 2. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- B. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 4. Parallelism measurement shall exclude any effect of mark on top surface of package.

Description: Compatible Device

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Tolerances:</u> Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-BGA-2004 Drawing	Finish: N/A Weight: 78.24	STATUS: Released	SHEET: 3 OF 5	REV. A
		ENG: B. Schatz	DRAWN BY: D. Hauer	SCALE: 2:1
		FILE: GT-BGA-2004 Dwg	DATE: 5/27/14	



ITEM NO.	DESCRIPTION	Material	
1	Compression Screw	Aluminum Alloy	
2	Socket Lid	Aluminum Alloy	
3	Compression Plate	Aluminum Alloy	
4	IC Frame	Ultem	
5	Test Chip	N/A	
6	Shoulder Screw	Stainless Steel	
7	Socket Base	Aluminum Alloy	
8	Dowel Pin	Stainless Steel	
9	IC Guide	Torlon 4203	
10	Ball Guide	Kapton Polyimide/Cirlex	
11	Mounting Screw	Stainless Steel	
12	GT Elastomer	Conductive columns in Kapton Polyimide	
13	Target PCB	N/A	
14	Backing Plate	Aluminum Alloy	

Description: Exploded View

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-BGA-2004 Drawing



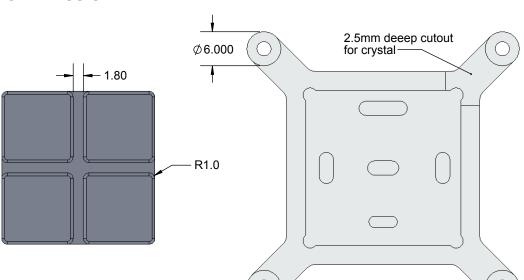
Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com

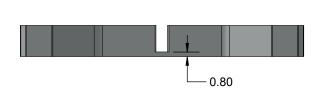
STATUS: Released	SHEET: 4 OF 5	REV. A
ENG: B. Schatz	DRAWN BY: D. Hauer	SCALE: 2:1
FILE: GT-BGA-2004 Dwg	DATE: 5/27/14	

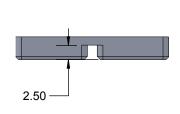
SOCKET BASE

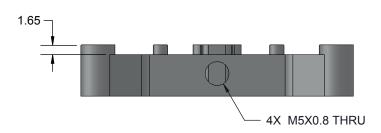
2.00 (4x) —

COMPRESSION PLATE









BACKING PLATE

Description: Base, Compression & Backing PI

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

GT-B	GA-20	04 Dr	awing



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STATUS: Released	SHEET: 5 OF 5	REV. A
ENG: B. Schatz	DRAWN BY: D. Hauer	SCALE: 3:2
FILE: GT-BGA-2004 Dwg	DATE: 5/27/14	